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- Flatlink Interface Utilizes Low Power Differential Signalling(LVDS)
- Suitable for Notebook Application
- **XGA** Resolution
- Six Bit System Interface
- **Support Mainstream Data and Gate Drivers**
- **Optional Configurable Pins**

- Low Voltage CMOS 3.3 V Technology
- 65 MHz Phase-Lock Input
- 100-pin TQFP Package for Compact LCD Module
- Tolerates 4 kV HBM ESD for LVDS Pins and 2 kV HBM for Others
- **Improved Jitter Tolerance**

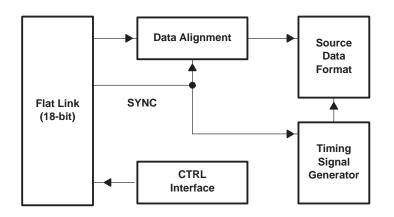
description

The SN75LVDS88 (LVDS panel timing controller) integrates a Flatlink signal interface with a TFT LCD timing controller. It resides in the LCD panel and provides interface between the graphic controller and a TFT LCD panel.

The SN75LVDS88 accepts host data through 3 pairs of inputs (18-bits) making up the LVDS bus, which is a low-EMI high-throughput interface. SN75LVDS88 then reformats the received image data into a specific data format and synchronous timing suitable for driving LCD panel column and row drivers. This device supports XGA resolution.

The SN75LVDS88 is easily configured by several selection terminals and is equipped with default timing specifications to support mainstream gate and source drivers on the market.

block diagram





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pin assignment

MODE1 MODE0 DBS VSS VSS CSS GNDA GNDA GND1 NC CLKP A2P A2P GNDD SHTDN VDDD TEST1 A2M A1M AOM AOP ЯN A MODE2 1 75 TP1 C CPV C 2 D OPOL 74 3 73 🗅 VSS VSS 🗆 4 72 OB0(OR0) STV 5 71 OE1 OB1(OR1) 6 70 REV_E 7 69 OB2(OR2) VDD [8 68 🛛 VSSIO REV_O 67 OB3(OR3) 9 OE2 [10 66 🛛 OB4(OR4) TP2 🗆 11 65 VDDIO VS<u>SIO</u> □ CLK □ 12 64 OB5(OR5) 13 SN75LVDS88 OG0 63 VDDIO [14 62 TEST2 🗆 OG1 15 61 ER5(EB5) 🗅 OG2 16 60 VSSIO [🗅 VDDIO 17 59 ER4(EB4) 58 🗆 OG3 18 57 🗅 OG4 ER3(EB3) [19 VDDIO 20 56 ER2(EB2) [21 ER1(EB1) [22 VSSIO [23 55 🗋 OG5 54 OR0(OB0) 53 VDDIO ER0(EB0) 24 52 OR1(OB1) EG5 🗆 25 51 OR2(OB2) OR5(OB3) [VSSIO [OR4(OB4) [OR3(OB3) [

TQFP PACKAGE (TOP VIEW)



Terminal Functions

TERMINAL					
NAME	NO.	1/0	DESCRIPTION		
A0M/A0P	81,82	1	Flatlink 1 st data pair		
A1M/A1P	83, 84	1	Flatlink 2 nd data pair		
A2M/A2P	85, 86	1	Flatlink 3 rd data pair		
CLK	44	0	CD bus clock		
CLK	13	0	CD bus clock (180 degree out of phase)		
CLKM/CLKP	87, 88	1	Flatlink clock pair		
CPV	3	0	Gate driver clock		
DBS	97	1	Data bus sequence		
EPOL	42	0	Even RGB data stream polarity indicator		
ER0ER5	24,22,21	0	Even red (blue) data bus, controlled by DBS Pin, 0 = red, 1 = blue		
(EB0)(EB5)	19,18,16				
(ER0)(ER5) EB0EB5	41,39,38 36,35,33	0	Even blue (red) data bus, controlled by DBS Pin, 0 = blue, 1 = red		
GND1	91	Р	PLL ground for LVDS		
MODE0	98	1	Default timing selection pin 0		
MODE1	99	1	Default timing selection pin 1		
MODE2	1	1	Default timing selection pin 2		
NC	76, 77, 89, 90	NC	NC terminals [†]		
OE1, OE2	6, 10	0	Gate driver output enable		
OG0OG5	63,61,60 58,57,55	0	Odd green data bus		
OPOL	74	0	Odd RGB data stream polarity indicator		
OR0OR5 (OB0)(OB5)	54,52,51 50,49,47	0	Odd red (blue) data bus, controlled by DBS Pin, 0 = red, 1 = blue		
(OR0)(OR5) OB0OB5	72,70,69 67,66,64	0	Odd blue (red) data bus, controlled by DBS Pin, 0 = blue, 1 = red		
POLEN	95	1	Output data polarity control enable /disable		
REV_E	7	0	CD line/dot inversion control signal		
REV_O	9	0	CD line/dot inversion control signal (180 degree of phase)		
RSTZ	93	1	Reset, active low		
SHTDN	79	I	System shutdown control, active low		
SP	46	0	Data bus starting pulse		
STV	5	0	Gate driver starting pulse		
TEST1, TEST2	100, 15	1	Test points [†]		
TP1, TP2	2, 11	0	CD output control signal		
VDDA	94	Р	PLL power for LVDS		
GNDA	92	Р	Analog ground for LVDS		
VDDD	78	Р	Digital power supply for LVDS		
GNDD	80	Р	Digital power ground for LVDS		
VDD	8,71,75	Р	Digital power		
VSS	4,73,96	Р	Digital ground		
VDDIO		Р	I/O power		
VSSIO		Р	I/O ground		

[†] Terminals must be connected to ground.

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options

output control

	PIN NO.	INTERNAL C	ONNECTION	DESCRIPTION
FININAME		REQUIRED	SUGGESTED	DESCRIPTION
MODE0 MODE1 MODE2	98 Pull-up 99 Pull-up 1 Pull-down			Default timing selection pin 0 Default timing selection pin 1 Default timing selection pin 2
POLEN		Pull-down		0 = Output data reverse disable 1 = Output data reverse enable
DBS				Data bus sequence 0 = normal (RGB) 1 = reverse (BGR)

NOTE: DBS and POLEN functions must not be enabled together. The option pins must be connected to ground or VDD.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V _{CC} ‡	
Voltage range at any terminal	
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range, T _{stg}	
Electrostatic discharge: Class 3 A	
Class 2 B	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡] All voltage values are with respect to the GND terminals unless otherwise noted.

DISSIPATION RATING TABLE

$\begin{array}{c} PACKAGE & T_{A} \leq 25^\circ C \\ POWER RATING \end{array}$		OPERATING FACTOR [§] ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
PFD	1.548 W	12 mW	1.012 W		

§ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.



recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	3	3.3	3.6	V	
High-level input voltage, VIH		2			
Low-level input voltage, VIL	SHTDN			0.8	V
Magnitude of differential input voltage, $ V_{ID} $		0.1		0.6	V
Common–mode input voltage, VIC		$\frac{ V_{ID} }{2}$		$2.4 - \frac{ V_{ID} }{2}$	V

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VIT+	Positive-going differential input voltage threshold				100	mV
V _{IT}	Negative-going differential input voltage threshold		-100			mV
		Disabled, all inputs to ground			360	μA
		Enabled, AnP at 1 V and AnM at 1.4 V, $t_{\rm C}$ = 15.38 ns		80		mA
ICC Quiescent current	Quiescent current (average)	Enabled, $C_L = 8 \text{ pF}$, Grayscale pattern , $t_C = 15.38 \text{ ns}$		100		
		Enabled, $C_L = 8 \text{ pF}$, Worst-case pattern , $t_C = 15.38 \text{ ns}$		120		
IIН	High-level input current (SHTDN)	VIH = VCC			±20	μA
Ι _Ι	Low-level input current (SHTDN)	$V_{IL} = 0 V$			±20	μΑ
I _{IN}	Input current (A inputs)	$0 V \leq V_{I} \leq 2.4 V$			±20	μA
IOZ	High-impendance output current	$V_{O} = 0 V \text{ or } V_{CC}$			±10	μΑ

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. [‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for the negative-going input voltage threshold only.

timing requirements

		MIN	TYP MAX	UNIT
t _c §	Input clock period	14.7	31.25	ns
t _{su} /t _h	Input set up or hold time	550		ps

 t_c is defined as the mean duration of a minimum of 32,000 clock periods.

output buffer rating

	MIN	TYP	MAX	UNIT
STV, SP		4		mA
CLK, CLK		12		mA
Data bus and remaining outputs		8		mA



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switching characteristics

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t dr1	Input clock rising to output clock rising delay	$C_{I} = 100 \text{pF}$	10		40	ns
^t df1	Input clock rising to output clock falling delay	θ[= 100 βi	10		40	ns
^t su1	Data set up time, E/O RGB to CLK↑	0 100 5	10		20	ns
^t h1	Data hold time, CLK↑ to E/O RGB		10		20	ns
^t (RSKM)	Receiver input skew margin, See Note 4	t_{C} = 15.38 ns (±0.2%), Input clock jitter < 50 ps, See Note 5	550	700		ps
t _{en}	Enable time, SHTDN to phase lock			1		ms
^t dis	Disable time, SHTDN to off state			250		ns
^t su2	SP setup time	0 15 -5	10		20	ns
^t h2	SP pulse hold time	C _{sp} = 15 pF	10		20	ns

NOTES: 1. tRSKM is the timing margin available to allocate to the transmitter and interconnection skews and clock jitter. The value of this

parameter at clock periods other than 15.38 ns can be calculated from $t_{RSKM} = \frac{t_c}{14}$ -300 ps.

2. |Input clock jitter | is the magnitude of the change in the input clock period.

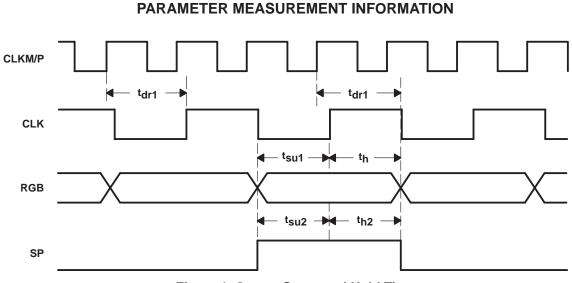


Figure 1. Output Setup and Hold Time



REFERENCE TIMING DIAGRAM

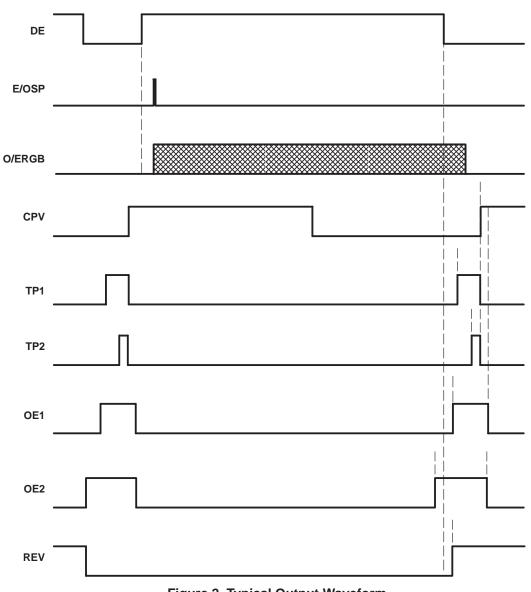


Figure 2. Typical Output Waveform



PARAMETER MEASUREMENT INFORMATION

functional description

Flatlink

The core of the Flatlink is TIs original 86A LVDS receiver which has three data channels for the 18-bit color plus one clock channel.

data alignment

The data alignment block supports dual bus dual port column driver configuration. When interfacing a 2-port column driver, the controller arranges pixels in odd and even order, then distributes them to odd and even buses and each connects to either of the driver ports. Under this setup, the controller outputs one clock, one or two data polarities (depends on driver), and one inverse (support line inversion) signal to the drivers.

output formatting

The output formatting provides several functions to reduce EMI, noise, and timing delay arrangement. These functions are controllable through some optional pins. See the registers and options section for reference.

- Reverse Polarity Generation
 When enable this function generates polarity indication signals. This occurs when the number of transitions in the output data bus exceeds 18-bits compared to the previous output under normal polarity. The polarity signal will be active and the output will be the opposite polarity to reduce transition
- Line Inversion
 When enabled, the REV_O and REV_E terminals will output the same line inversion control signals but in opposite polaritys.

timing control

- Source Shifted Clock(SSC)
 The master data clock could be arranged to have an intentional phase delay relative to the output data, which helps the system engineer tune the clock to latch the data correctly regardless of the characteristics presented by the PCB and the layout.
- Horizontal Starting pulses ESP and OSP terminals are used as the horizontal starting pulses outputs pins. Their output are one HCLK period ahead of the RGB data stream
- Horizontal Clock ECLK and OCLK terminals are responsible for the clock pulses, based on the XGA resolution when its frequency is at 32.5 MHz.
- CD Data Latch Pulse TP1 and TP2 provide the column driver input latch and output enable signals.
- Gate Driver Clock The CPV terminal output the clock pulses to the gate drivers as the horizontal sync timing in its CRT counter part.
- Gate Driver Starting Pulse The vertical starting pulse automatically generates at the start of every frame.
- Gate Driver Output Enable The OE1 and OE2 terminals provide the gate output enabale signals.



PARAMETER MEASUREMENT INFORMATION

functional description (continued)

vertical/horizontal reference generator

This block provides vertical and horizontal reference points for timing control. Vsync, Hsync, and ENAB signals along with the auto detection function determine when the video from the host is valid.

power-up procedure

Due to the uncertainty of registers and counters in the driver, SN75LVDS88 combines the input from both reset and Vsync to blank the output and simultaneously resets the content of drivers (see Figure 3).

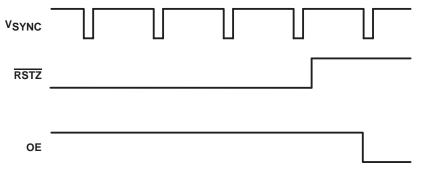
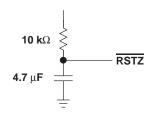


Figure 3. Reset Waveform

It is recommended that the following circuit be used to ensure the device is reset for more than 5 ms after power up.





ORGB

ERGB



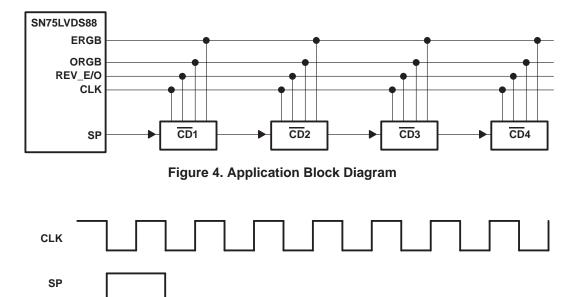
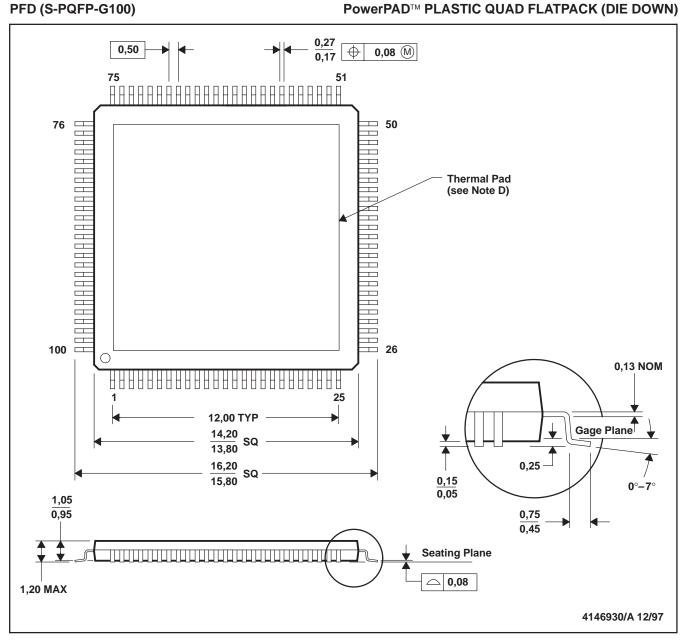


Figure 5. Data Output Format



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MECHANICAL DATA



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. The package thermal performance may be enhanced by attaching an external heatsink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MS-026

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